

**Amendments to the Claims**

1. (currently amended) A light-emitting structure, comprising:  
a plurality of light-emitting diodes each having an anode and a cathode and each configured to emit a respective color of light; and  
a resistive member carried over at least one of said anode and said cathode of each of said diodes;  
a plurality of conductive contacts spaced over the resistive member of each of said diodes; and  
a conductive wire coupled to at least a selected one of the contacts of each of said diodes to thereby form an interconnected string of diodes regardless of the orientation of each of said diodes.
2. (original) the structure of claim 1, wherein said resistive member has a resistivity and a cross section configured to realize a predetermined resistance.
3. (original) The structure of claim 1, wherein said resistive member comprises a resistive film.
4. (original) The structure of claim 1, wherein said resistive member comprises a thin film resistor.
5. (original) The structure of claim 1, wherein said resistive member comprises a thick film resistor.
6. (currently amended) The structure of claim 1, further including a conductive film inserted between said each resistive member and said its respective light-emitting diode.
7. (currently amended) The structure of claim 1, wherein said wire has a substantially flat cross section resistive member is carried over said anode and further including an interconnect member coupled to a selected one of said cathode and said resistive member.

8. (currently amended) The structure of claim 1 7, wherein said ~~interconnect member~~ ~~wire comprises a metal alloy is coupled through at least one contact.~~

9. (withdrawn) The structure of claim 7, wherein said interconnect member includes a tab that couples to said selected one.

10. (withdrawn) The structure of claim 7, further including a wire bond that couples said interconnect member to said selected one.

11. (currently amended) The structure of claim 1, ~~further including solder which joins said wire to the selected contact of each of said diodes wherein said resistive member is carried over said cathode and further including an interconnect member coupled to a selected one of said anode and said resistive member.~~

12. (currently amended) The structure of claim 1 11, wherein said ~~interconnect member~~ ~~wire~~ is coupled ~~through at least one to a plurality of contacts of at least one of said diodes.~~

13. (withdrawn) The structure of claim 11, wherein said interconnect member includes a tab that couples to said selected one.

14. (withdrawn) The structure of claim 11, further including a wire bond that couples said interconnect member to said selected one.

15. (currently amended) The structure of claim 1, wherein each of said light-emitting diodes is a semiconductor light-emitting diode.

16. (currently amended) The structure of claim 1, wherein each of said light-emitting diodes is an organic light-emitting diode.

17. (currently amended) The structure of claim 1, wherein each of said light-emitting diodes is a polymer light-emitting diode.

18. (withdrawn) A light-emitting structure, comprising:  
a light-emitting diode having an anode and a cathode;  
a resistive member carried over a selected one of said anode and said cathode;  
and  
first and second contacts respectively on first and second portions of said resistive member.
19. (withdrawn) The structure of claim 18, further including a conductive film inserted between said resistive member and said light-emitting diode.
20. (withdrawn) The structure of claim 18, wherein said resistive member has a resistivity and a cross section configured to realize predetermined resistances between said first and second contacts and said light-emitting diode.
21. (withdrawn) The structure of claim 18, further including first and second interconnect members respectively coupled to said first and second contacts.
22. (withdrawn) The structure of claim 18, wherein said resistive member comprises a resistive film.
23. (withdrawn) The structure of claim 18, wherein said resistive member comprises a thin film resistor.
24. (withdrawn) The structure of claim 18, wherein said resistive member comprises a thick film resistor.
25. (withdrawn) The structure of claim 18, wherein said light-emitting diode is a semiconductor light-emitting diode.
26. (withdrawn) The structure of claim 18, wherein said light-emitting diode is an organic light-emitting diode.
27. (withdrawn) The structure of claim 18, wherein said light-emitting diode is a polymer light-emitting diode.

28. (currently amended) A light-emitting structure, comprising:  
~~a plurality of light-emitting diodes each having an anode and a cathode and each configured to emit a respective color of light; and at least first and second spaced a plurality of resistive members carried spaced over a selected at least one of said anode and said cathode of each of said diodes wherein each of said resistive members has a different resistance;~~  
~~at least one conductive contact carried on each of said resistive members; and a conductive wire coupled through a contact to a respective one of the resistive members of each of said diodes to thereby form an interconnected string of diodes that will each carry a respective current when a voltage is applied to said wire.~~

29. (currently amended) The structure of claim 28, further including a conductive film inserted between each of said resistive members and ~~said light emitting its respective diode.~~

30. (currently amended) The structure of claim 28, wherein each of said resistive members has a resistivity and a cross section configured to realize [[a]] ~~its respective predetermined~~ resistance.

31. (currently amended) The structure of claim 28, ~~wherein said wire has a substantially flat cross section further including an interconnect member coupled to a selected one of said resistive films.~~

32. (currently amended) The structure of claim 28, wherein ~~said each~~ resistive member comprises a resistive film.

33. (original) The structure of claim 28, wherein each resistive member comprises a thin film resistor.

34. (original) The structure of claim 28, wherein each resistive member comprises a thick film resistor.

35. (original) The structure of claim 28, wherein said light-emitting diode is a semiconductor light-emitting diode.

36. (original) The structure of claim 28, wherein said light-emitting diode is an organic light-emitting diode.

37. (original) The structure of claim 28, wherein said light-emitting diode is a polymer light-emitting diode.